

Film Capacitors

EMI Suppression Capacitors (MKP)

Series/Type:B32921C/D ... B32928C/DDate:September 2019

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EMI suppression capacitors (MKP)

X2 / 305 V AC

B32921C/D ... B32928C/D

Typical applications

- X2 class for interference suppression
- "Across the line" applications

Climatic

- Max. operating temperature: 110 °C
- Climatic category (IEC 60068-1:2013): 40/105/56 (ENEC10) 40/110/56 (ENEC15)

Construction

- Dielectric: polypropylene (MKP)
- Plastic case (UL 94 V-0)
- Epoxy resin sealing (UL 94 V-0)

Features

- Very small dimensions
- Self-healing properties
- RoHS-compatible
- Halogen-free capacitors available on request

Terminals

- Parallel wire leads, lead-free tinned
- Special lead lengths available on request

Marking

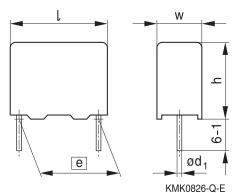
Manufacturer's logo, lot number, date code, rated capacitance (coded), cap. tolerance (code letter), rated AC voltage, series number, sub-class (X2), dielectric code (MKP), climatic category, passive flammability category, approvals.

Delivery mode

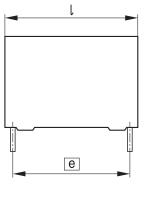
Bulk (untaped) Taped (Ammo pack or reel) For taping details, refer to chapter "Taping and packing"

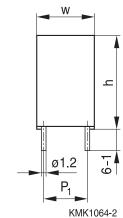
Dimensional drawings

Drawing 1









Dimensions in mm

 $P_1 = 20.3 \text{ mm}$

Lead diameter d1 ±0.05	Туре	Drawing
0.6	B32921	1
0.8	B32922	1
0.8	B32923	1
0.8	B32924	1
1.0	B32926	1 / 2 ¹⁾
1.2	B32928	2
	diameter d1±0.05 0.6 0.8 0.8 0.8 0.8 1.0	diameter d1±0.05 0.6 B32921 0.8 B32923 0.8 B32924 1.0

1) A few individual types only

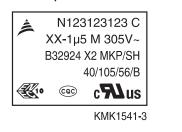
Please read *Cautions and warnings* and *Important notes* at the end of this document.

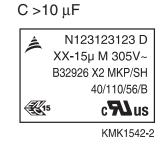




Marking Examples

$C \leq 10 \ \mu F$





Approvals

Approval marks	Standards	Certificate
IIIdiks	EN 00004 44-0044	
10	EN 60384-14:2014 IEC 60384-14:2013	40010694 (approved by VDE) (C \leq 10 $\mu F)$
EK15	EN 60384-14:2014 IEC 60384-14:2013	E97863 (approved by UL)
<i>1</i> .	UL 1414:2000 UL 1283:2005	E97863 / E157153
c '91	CSA C22.2 No.1:2004 CSA C22.2 No.8:2013	E97863 / E157153 (approved by UL)
	CQC (GB/T 14472-1998):1998	CQC06001015331 / CQC06001016454 (C \leq 10 μ F)
c 91 us	UL 60384-14:2014 CSA E60384-14:2013	E97863 (approved by UL)

Notes:	Effective January 2014, only for EMI supression capacitors:
	 UL 60384-14:2014 certification replaces both UL 1414:2000 and UL 1283:2005 standards.
	 CSA C22.2 No.1.2004 and CSA C22.2 No.8:2013 are replaced by CSA E60384-14:2013.
	 References like 1414, 1283 are removed from the capacitor marking.
	Capacitors under UL 1414:2000, UL 1283:2005 produced during or before 2013, are accepted under UL scope.
	Capacitors under CSA C22.2 No.1:2004 / CSA C22.2 No.8:2013 produced during or before 2013, are accepted under cUL scope.





X2 / 305 V AC

Overview of available types

Lead spacing	10 mm	15 mm	22.5 mm	27.5 mm	37.5 mm	52.5 mm
Туре	B32921C/D	B32922C/D	B32923C/D	B32924C/D	B32926C/D	B32928C/D
C _R (μF)						
0.010						
0.022						
0.033						
0.047						
0.068						
0.10						
0.15						
0.22						
0.33						
0.47						
0.68						
1.0						
1.5						
2.2						
3.3						
3.9						
4.7						
5.6						
6.8						
8.2						
10						
15						
20						
25						
30						



X2	B32921C/D
	X2 / 305 V AC

Ordering codes and packing units (lead spacing 10.0 mm)

C _R	Max. dimensions	Ordering code	Ammo pack	Reel	Untaped	Pins
	$w \times h \times l$	(composition see below)				
μF	mm		pcs./MOQ	pcs./MOQ	pcs./MOQ	
0.010	$4.0 \times 9.0 \times 13.0$	B32921C3103+*** ◆	4000	6800	4000	2
0.022	$4.0\times 9.0\times 13.0$	B32921C3223+*** ◆	4000	6800	4000	2
0.033	$4.0\times 9.0\times 13.0$	B32921C3333+*** ◆	4000	6800	4000	2
0.047	$5.0 \times 11.0 \times 13.0$	B32921C3473+*** ◆	3320	5200	4000	2
0.068	$6.0\times12.0\times13.0$	B32921C3683+***	2720	4400	4000	2
0.10	$6.0\times12.0\times13.0$	B32921C3104M***	2720	4400	4000	2

Preferred type

MOQ = Minimum Order Quantity, consisting of 4 packing units. Further intermediate capacitance values on request.

Composition of ordering code

- + = Capacitance tolerance code:
 - $M = \pm 20\%$
 - K = ±10%

*** = Packaging code:

- 289 = Straight terminals, Ammo pack
- 189 = Straight terminals, Reel
- $\begin{array}{rl} \text{003} = & \text{Straight terminals, untaped} \\ & (\text{lead length 3.2 } \pm 0.3 \text{ mm}) \end{array}$
- 000 = Straight terminals, untaped (lead length 6 -1 mm)



X2 B32

B32922C/D

X2 / 305 V AC

Ordering codes and packing units (lead spacing 15.0 mm)

C _R	Max. dimensions	Ordering code	Ammo pack	Reel	Untaped	Pins
	$w \times h \times l$	(composition see below)				
μF	mm		pcs./MOQ	pcs./MOQ	pcs./MOQ	
0.033	$5.0\times10.5\times18.0$	B32922C3333K***	4680	5200	4000	2
0.047	$5.0\times10.5\times18.0$	B32922C3473K***	4680	5200	4000	2
0.068	$5.0\times10.5\times18.0$	B32922C3683K*** ◆	4680	5200	4000	2
0.10	5.0 imes 10.5 imes 18.0	B32922C3104+*** ◆	4680	5200	4000	2
0.15	$6.0\times12.0\times18.0$	B32922C3154+*** 🔶	3840	4400	4000	2
0.22	7.0 imes 12.5 imes 18.0	B32922C3224+*** ◆	3320	3600	4000	2
0.33	8.0 × 14.0 × 18.0	B32922C3334M*** ◆	2920	3000	2000	2
0.33	8.5 imes 14.5 imes 18.0	B32922D3334K***	2720	2800	2000	2
0.47	$9.0 \times 17.5 \times 18.0$	B32922C3474+*** 🔶	2560	2800	2000	2
0.68	$11.0\times18.5\times18.0$	B32922C3684+*** ◆	_	2200	1200	2

Preferred type

MOQ = Minimum Order Quantity, consisting of 4 packing units. Further intermediate capacitance values on request.

- + = Capacitance tolerance code:
 - $M = \pm 20\%$ $K = \pm 10\%$

- *** = Packaging code:
 - 289 = Straight terminals, Ammo pack
 - 189 = Straight terminals, Reel
 - $\begin{array}{rl} \text{003} = & \text{Straight terminals, untaped} \\ & (\text{lead length 3.2 } \pm 0.3 \text{ mm}) \end{array}$
 - 000 = Straight terminals, untaped (lead length 6 -1 mm)



B32923C/D X2 / 305 V AC



Ordering codes and packing units (lead spacing 22.5 mm)

C _R	Max. dimensions	Ordering code	Ammo pack	Reel	Untaped	Pins
	$w \times h \times l$	(composition see below)				
μF	mm		pcs./MOQ	pcs./MOQ	pcs./MOQ	
0.22	$6.0\times15.0\times26.5$	B32923C3224+***	2720	2800	2880	2
0.33	$6.0\times15.0\times26.5$	B32923C3334M***	2720	2800	2880	2
0.33	$7.0 \times 16.0 \times 26.5$	B32923D3334K***	2320	2400	2520	2
0.47	$8.5 \times 16.5 \times 26.5$	B32923C3474+***	1920	2000	2040	2
0.68	$10.5\times16.5\times26.5$	B32923C3684+***	1560	1600	2160	2
1.0	$11.0 \times 20.5 \times 26.5$	B32923C3105+*** ◆	1480	1400	2040	2
1.5	$12.0\times22.0\times26.5$	B32923C3155M***	—	—	1800	2
2.2	$14.5\times29.5\times26.5$	B32923C3225+***		—	1040	2

Preferred type

MOQ = Minimum Order Quantity, consisting of 4 packing units. Further intermediate capacitance values on request.

- + = Capacitance tolerance code:
 - $M = \pm 20\%$
 - $K = \pm 10\%$

- *** = Packaging code:
 - 289 = Straight terminals, Ammo pack
 - 189 = Straight terminals, Reel
 - 003 = Straight terminals, untaped (lead length 3.2 ±0.3 mm)
 - 000 = Straight terminals, untaped (lead length 6 -1 mm)



X2 B32924C/D X2/305 V AC

Ordering codes and packing units (lead spacing 27.5 mm)

C _R	Max. dimensions	Ordering code	Ammo pack	Reel	Untaped	Pins
	$w \times h \times l$	(composition see below)				
μF	mm		pcs./MOQ	pcs./MOQ	pcs./MOQ	
0.68	$11.0 \times 19.0 \times 31.5$	B32924C3684+***	_	1400	1280	2
1.0	$11.0 \times 19.0 \times 31.5$	B32924C3105+***	—	1400	1280	2
1.5	$12.5\times21.5\times31.5$	B32924C3155+*** ◆	—	1200	1120	2
2.2	$14.0\times24.5\times31.5$	B32924C3225+***	—	—	1040	2
3.3	$16.0\times32.0\times31.5$	B32924D3335K***	—	—	880	2
3.3	$18.0 \times 27.5 \times 31.5$	B32924C3335M***	_	_	800	2
4.7	$18.0\times33.0\times31.5$	B32924C3475M***	—	—	800	2
4.7	$21.0 \times 31.0 \times 31.5$	B32924D3475K***	—	—	720	2
5.6	$22.0\times36.5\times31.5$	B32924C3565+***	—	-	784	2

Preferred type

MOQ = Minimum Order Quantity, consisting of 4 packing units. Further intermediate capacitance values on request.

- + = Capacitance tolerance code:
 - $M = \pm 20\%$
 - $K = \pm 10\%$

- *** = Packaging code:
 - 289 = Straight terminals, Ammo pack
 - 189 = Straight terminals, Reel
 - 003 = Straight terminals, untaped (lead length 3.2 ± 0.3 mm)
 - 000 = Straight terminals, untaped (lead length 6 - 1 mm)



B32926C/D X2 / 305 V AC



Ordering codes and packing units (lead spacing 37.5 mm)

C _R	Max. dimensions	Ordering code	Ammo pack	Reel	Untaped	Pins
	$w \times h \times I$	(composition see below)				
μF	mm		pcs./MOQ	pcs./MOQ	pcs./MOQ	
2.2	$14.0\times25.0\times41.5$	B32926C3225+***	_	-	1380	2
3.3	$16.0 \times 28.5 \times 41.5$	B32926C3335+***	_	—	800	2
3.9	$16.0 \times 28.5 \times 41.5$	B32926C3395+***	_	—	800	2
4.7	$18.0 \times 32.5 \times 41.5$	B32926C3475+***	_	—	720	2
5.6	$18.0 \times 32.5 \times 41.5$	B32926C3565+***	_	—	720	2
6.8	$20.0\times39.5\times42.0$	B32926C3685+***	_	_	640	2
8.2	$20.0\times39.5\times42.0$	B32926C3825+***	_	—	640	2
10	$28.0\times42.5\times42.0$	B32926C3106+***	_	—	440	2
15	$30.0\times45.0\times42.0$	B32926C3156M***	—	_	400	2
15	$33.0\times48.0\times42.0$	B32926D3156+***	_	_	180	4

MOQ = Minimum Order Quantity, consisting of 4 packing units.

Further intermediate capacitance values on request.

Composition of ordering code

- + = Capacitance tolerance code:
 - $M = \pm 20\%$

 $K = \pm 10\%$

- *** = Packaging code:
 - 289 = Straight terminals, Ammo pack
 - 189 = Straight terminals, Reel
 - $\begin{array}{rl} \text{003} = & \text{Straight terminals, untaped} \\ & (\text{lead length 3.2 } \pm 0.3 \text{ mm}) \end{array}$
 - 000 = Straight terminals, untaped (lead length 6 -1 mm)





B32928C/D X2 / 305 V AC

Ordering codes and packing units (lead spacing 52.5 mm)

C _R	Max. dimensions $w \times h \times l$	Ordering code (composition see below)	Ammo pack	Reel	Untaped	Pins
μF	mm		pcs./MOQ	pcs./MOQ	pcs./MOQ	
20	30.0 imes 45.0 imes 57.5	B32928C3206+***	_	_	280	4
25	$35.0\times50.0\times57.5$	B32928C3256+***	—	—	108	4
30	$35.0\times50.0\times57.5$	B32928C3306M***	_	_	108	4

MOQ = Minimum Order Quantity, consisting of 4 packing units. Further intermediate capacitance values on request.

- + = Capacitance tolerance code:
 - M =±20%
 - $K = \pm 10\%$

- *** = Packaging code:
 - 289 = Straight terminals, Ammo pack
 - 189 = Straight terminals, Reel
 - $\begin{array}{rl} \text{003} = & \text{Straight terminals, untaped} \\ & (\text{lead length 3.2 } \pm 0.3 \text{ mm}) \end{array}$
 - 000 = Straight terminals, untaped (lead length 6 -1 mm)



X2/305 V AC



Technical data

Reference standard: IEC 60384-14:2013. All data given at T = 20 °C, unless otherwise specified.

	1				
Max. operating temperature $T_{op,max}$	+110 °C				
Dissipation factor tan δ (in 10 ⁻³)	at	C _R ≤0.1 μF	0.1μF <c<sub>R≤2</c<sub>	2.2 μF	C _R >2.2 μF
at 20 °C (upper limit values)	1 kHz	1.0	1.0		2.0
	100 kHz	5.0	-		_
Insulation resistance R _{ins} or	C _R ≤0.33 μF	C _R >0.33 µ	ار F		•
time constant $\tau = C_R \cdot R_{ins}$ at 20 °C,	100 000 MΩ	30 000 s			
rel. humidity \leq 65%					
(minimum as-delivered values)					
DC test voltage	2121 V, 2 s (C \leq 10 $\mu F)$ / 1312 V, 2 s (C $>$ 10 $\mu F)$				
The repetition of this DC voltage test r	nay damage th	e capacito	r. Special care	e must	be taken in
case of use several capacitors in a pa	rallel configura	tion.			
Passive flammability category	В				
Maximum continuous DC voltage V_{DC}	630 V				
Maximum continuous AC voltage V_{AC}	310 V (50/60	Hz)			
Rated AC voltage (IEC 60384-14)	305 V (50/60	Hz)			
Operating AC voltage V _{op} at high	$T_{op} \le 110 \ ^{\circ}C$	١	$V_{op} = V_{AC}$	(cor	ntinuously)
temperature	$T_{op} \le 110 \ ^{\circ}C$	١	$V_{\rm op} = 1.25 \cdot V_{\rm A}$	c (100	00 h)
Damp heat test	56 days / 40 °	°C / 93% re	lative humidity	/	
Limit values after damp heat test	Capacitance of	change $ \Delta 0$	C/C ≤ 5	%	
	Dissipation fa	ctor chang	$\Delta \tan \delta \leq 5$.10 ⁻³ (a	at 1 kHz)
		-	≤ 1	.0 • 10	⁻³ (at 10 kHz)
	Insulation resistance R _{ins}				minimum
	or time constant $\tau = C_B \cdot R_{ins}$			deliver	ed values





Pulse handling capability

"dV/dt" represents the maximum permissible voltage change per unit of time for non-sinusoidal voltages, expressed in $V/\mu s$.

" k_0 " represents the maximum permissible pulse characteristic of the waveform applied to the capacitor, expressed in V²/µs.

Note:

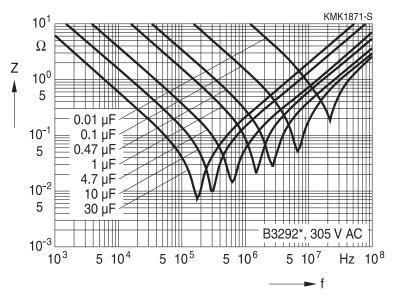
The values of dV/dt and k_0 provided below must not be exceeded in order to avoid damaging the capacitor.

dV/dt and k₀ values

Lead spacing	10 mm	15 mm	22.5 mm	27.5 mm	37.5 mm	52.5 mm
dV/dt in V/µs	475	340	170	120	80	50
k₀in V²/µs	408500	292400	146200	103200	68800	43200

Impedance Z versus frequency f

(typical values)

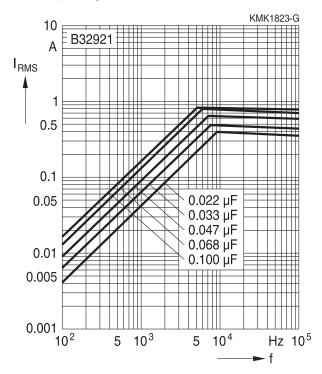




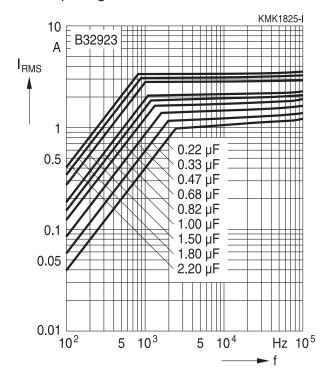


Permissible AC current I_{RMS} versus frequency f (for sinusoidal waveforms T_A ≤90 °C and ΔESR <100% from receipt condition)

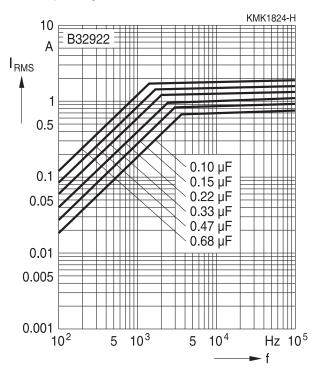
Lead spacing 10 mm

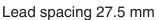


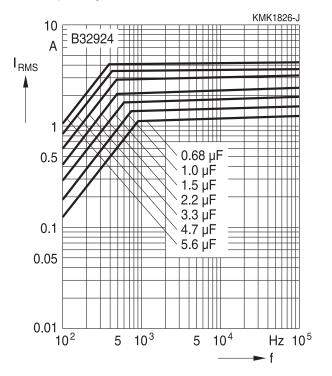
Lead spacing 22.5 mm



Lead spacing 15 mm





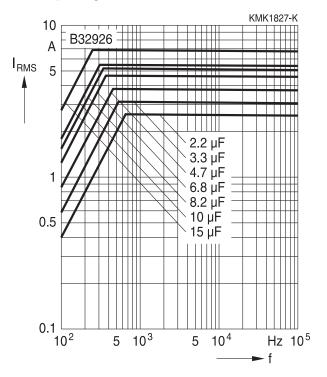




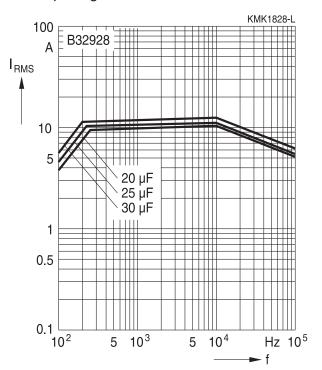


Permissible AC current I_{RMS} versus frequency f (for sinusoidal waveforms T_A ≤90 °C and Δ ESR <100% from receipt condition)

Lead spacing 37.5 mm



Lead spacing 52.5 mm





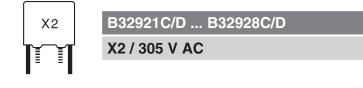
X2 / 305 V AC



Testing and Standards

Test	Reference	Conditions of test		Performance requirements
Electrical parameters Robustness of termina-	IEC 60384-14:2013 IEC 60068-2-21:2006	Voltage Proof:Between terminals: $4.3 \times V_R$ (DC), 1 minTerminals and enclosure: $2 V_R + 1500 V AC$ Insulation resistance, R _{ins} Capacitance, CDissipation factor, tan δ Tensile strength (test Ua1)Wire diameterTensile		Within specified limits Capacitance and tan δ within specified limits
tions		$0.5 < d_1 \le 0.8 \text{ mm}$ $0.8 < d_1 \le 1.25 \text{ mm}$	force 10 N 20 N	
Resistance to solder- ing heat	IEC 60068-2-20:2008, test Tb, method 1A	Solder bath temperature at 260 \pm 5 °C, immersion for 10 seconds		$\Delta C/C_0 \le 5\%$ tan δ within specified limits
Rapid change of temperature	IEC 60384-14:2013	T_A = lower category temperature T_B = upper category temperature Five cycles, duration t = 30 min.		No visible damage $ \Delta C/C_0 \le 5\%$ tan δ within specified limits
Damp heat, steady state	IEC 60384-14:2013	Test Ca 40 °C / 93% RH / 56 days		$\begin{array}{l} \mbox{No visible damage} \\ \Delta C/C_0 \leq 5\% \\ \Delta \mbox{ tan } \delta \leq 0.008 \mbox{ for } C \leq 1 \ \mu F \\ \Delta \mbox{ tan } \delta \leq 0.005 \mbox{ for } C > 1 \ \mu F \\ \mbox{Voltage proof} \\ R_{\mbox{ins}} \geq 50\% \mbox{ of initial limit} \end{array}$
Impulse test Endurance	IEC 60384-14:2013	3 impulses $T_B / 1.25 V_R / 1000$ hours, 1000 V_{RMS} for 0.1 s every hour		$\begin{array}{l} \mbox{No visible damage} \\ \Delta C/C_0 \leq 10\% \\ \Delta \mbox{ tan } \delta \leq 0.008 \mbox{ for } C \leq 1 \ \mu F \\ \Delta \mbox{ tan } \delta \leq 0.005 \mbox{ for } C > 1 \ \mu F \\ \mbox{Voltage proof} \\ R_{\mbox{ins}} \geq 50\% \mbox{ of initial limit} \end{array}$
Passive flammability	IEC 60384-14:2013	Flame applied for a period of time depending on capacitor volume		В
Active flammability	IEC 60384-14:2013	20 discharges at 2.5 kV + V_{R}		The cheesecloth shall not burn with a flame





Mounting guidelines

1 Soldering

1.1 Solderability of leads

The solderability of terminal leads is tested to IEC 60068-2-20:2008, test Ta, method 1.

Before a solderability test is carried out, terminals are subjected to accelerated ageing (to IEC 60068-2-2:2007, test Ba: 4 h exposure to dry heat at 155 °C). Since the ageing temperature is far higher than the upper category temperature of the capacitors, the terminal wires should be cut off from the capacitor before the ageing procedure to prevent the solderability being impaired by the products of any capacitor decomposition that might occur.

Solder bath temperature	235 ±5 °C
Soldering time	2.0 ±0.5 s
Immersion depth	2.0 +0/ -0.5 mm from capacitor body or seating plane
Evaluation criteria:	
Visual inspection	Wetting of wire surface by new solder ≥90%, free-flowing solder

1.2 Resistance to soldering heat

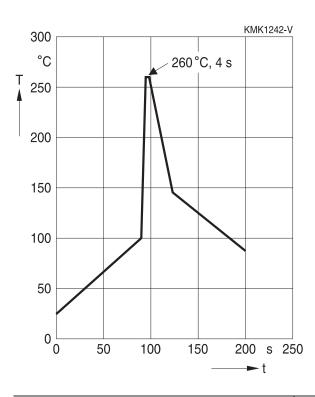
Resistance to soldering heat is tested to IEC 60068-2-20:2008, test Tb, method 1. Conditions:

Serie	S	Solder bath temperature	Soldering time
MKT	boxed (except $2.5 \times 6.5 \times 7.2$ mm) coated uncoated (lead spacing >10 mm)	260 ±5 °C	10 ±1 s
MFP			
MKP	(lead spacing >7.5 mm)		
MKT	boxed (case $2.5 \times 6.5 \times 7.2$ mm)		5±1 s
MKP MKT	(lead spacing ≤7.5 mm) uncoated (lead spacing ≤10 mm) insulated (B32559)		<4 s recommended soldering profile for MKT uncoated (lead spacing \leq 10 mm) and insulated (B32559)





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Immersion depth	2.0 +0/ -0.5 mm from capacitor body or seating plane
Shield	Heat-absorbing board, (1.5 \pm 0.5) mm thick, between capacitor body and liquid solder
Evaluation criteria:	
Visual inspection	No visible damage
$\Delta C/C_0$	2% for MKT/MKP/MFP 5% for EMI suppression capacitors
tan δ	As specified in sectional specification

1.3 General notes on soldering

Permissible heat exposure loads on film capacitors are primarily characterized by the upper category temperature T_{max} . Long exposure to temperatures above this type-related temperature limit can lead to changes in the plastic dielectric and thus change irreversibly a capacitor's electrical characteristics. For short exposures (as in practical soldering processes) the heat load (and thus the possible effects on a capacitor) will also depend on other factors like:

- Pre-heating temperature and time
- Forced cooling immediately after soldering
- Terminal characteristics: diameter, length, thermal resistance, special configurations (e.g. crimping)
- Height of capacitor above solder bath
- Shadowing by neighboring components
- Additional heating due to heat dissipation by neighboring components
- Use of solder-resist coatings

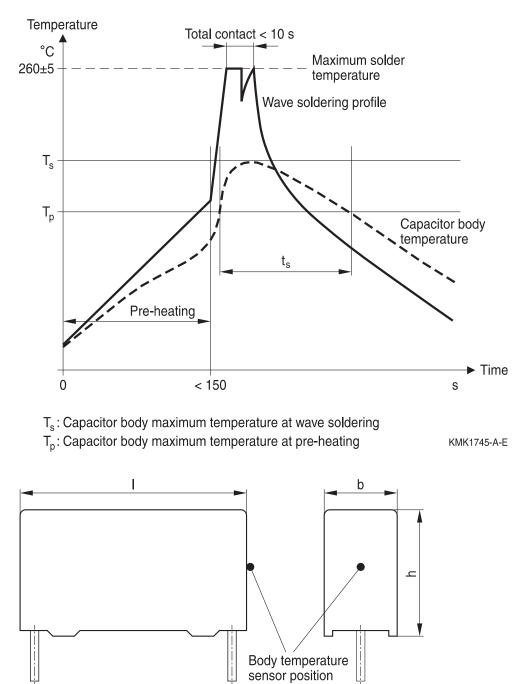




The overheating associated with some of these factors can usually be reduced by suitable countermeasures. For example, if a pre-heating step cannot be avoided, an additional or reinforced cooling process may possibly have to be included.

Recommendations

As a reference, the recommended wave soldering profile for our film capacitors is as follows:



Ρ

KMK1744-9-E



X2 / 305 V AC



Body temperature should follow the description below:

- MKP capacitor During pre-heating: T_p ≤110 °C During soldering: T_s ≤120 °C, t_s ≤45 s
- MKT capacitor During pre-heating: T_p ≤125 °C During soldering: T_s ≤160 °C, t_s ≤45 s

When SMD components are used together with leaded ones, the film capacitors should not pass into the SMD adhesive curing oven. The leaded components should be assembled after the SMD curing step.

Leaded film capacitors are not suitable for reflow soldering.

In order to ensure proper conditions for manual or selective soldering, the body temperature of the capacitor (T_s) must be \leq 120 °C.

One recommended condition for manual soldering is that the tip of the soldering iron should be <360 °C and the soldering contact time should be no longer than 3 seconds.

For uncoated MKT capacitors with lead spacings \leq 10 mm (B32560/B32561) the following measures are recommended:

- pre-heating to not more than 110 °C in the preheater phase
- rapid cooling after soldering

Please refer to our Film Capacitors Data Book in case more details are needed.





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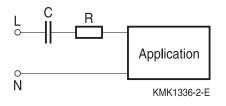
Application note for the different possible X1 / X2 positions

In series with the powerline (i.e. capacitive power supply)

Typical Applications:

- Power meters
- ECUs for white goods and household appliances
- Different sensor applications
- Severe ambient conditions

Basic circuit



Required features

- High capacitance stability over the lifetime
- Narrow tolerances for a controlled current supply

Recommended product series

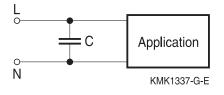
- B3293* (305 V AC) heavy duty with EN approval for X2 (UL Q1/2010)
- B3265* MKP series standard MKP capacitor without safety approvals
- B3267*L MKP series standard MKP capacitor without safety approvals
- B3292*H/J (305 V AC), severe ambient condition, approved as X2

In parallel with the powerline

Typical Applications:

Standard X2 are used parallel over the mains for reducing electromagnetic interferences coming from the grid. For such purposes they must meet the applicable EMC directives and standards.

Basic circuit



Required features

- Standard safety approvals (ENEC, UL, CSA, CQC)
- High pulse load capability
- Withstand surge voltages

Recommended product series

- B3292*C/D (305 V AC) standard series, approved as X2
- B3291* (330 V AC), approved as X1
- B3291* (530 V AC), approved as X1
- B3291* (550 V AC), approved as X1
- B3292*H/J (305 V AC), severe ambient condition, approved as X2



X2 / 305 V AC



Cautions and warnings

- Do not exceed the upper category temperature (UCT).
- Do not apply any mechanical stress to the capacitor terminals.
- Avoid any compressive, tensile or flexural stress.
- Do not move the capacitor after it has been soldered to the PC board.
- Do not pick up the PC board by the soldered capacitor.
- Do not place the capacitor on a PC board whose PTH hole spacing differs from the specified lead spacing.
- Do not exceed the specified time or temperature limits during soldering.
- Avoid external energy inputs, such as fire or electricity.
- Avoid overload of the capacitors.
- Consult us if application is with severe temperature and humidity condition.
- There are no serviceable or repairable parts inside the capacitor. Opening the capacitor or any attempts to open or repair the capacitor will void the warranty and liability of TDK Electronics.
- Please note that the standards referred to in this publication may have been revised in the meantime.

The table below summarizes the safety instructions that must always be observed. A detailed description can be found in the relevant sections of the chapters "General technical information" and "Mounting guidelines".

Торіс	Safety information	Reference chapter "General technical information"
Storage conditions	Make sure that capacitors are stored within the specified range of time, temperature and humidity conditions.	4.5 "Storage conditions"
Flammability	Avoid external energy, such as fire or electricity (passive flammability), avoid overload of the capacitors (active flammability) and consider the flammability of materials.	5.3 "Flammability"
Resistance to vibration	Do not exceed the tested ability to withstand vibration. The capacitors are tested to IEC 60068-2-6:2007. TDK Electronics offers film capacitors specially designed for operation under more severe vibration regimes such as those found in automotive applications. Consult our catalog "Film Capacitors for Automotive Electronics".	5.2 "Resistance to vibration"





X2 / 305 V AC

Topic	Safety information	Reference chapter "Mounting guidelines"
Soldering	Do not exceed the specified time or temperature limits during soldering.	1 "Soldering"
Cleaning	Use only suitable solvents for cleaning capacitors.	2 "Cleaning"
Embedding of capacitors in finished assemblies	When embedding finished circuit assemblies in plastic resins, chemical and thermal influences must be taken into account. Caution: Consult us first, if you also wish to embed other uncoated component types!	3 "Embedding of capacitors in finished assemblies"

Design of our capacitors

Our EMI capacitors use polypropylene (PP) film metalized with a thin layer of Zinc (Zn). The following key points have made this design suitable to IEC/UL testing, holding a minimum size.

- Overvoltage AC capability with very high temperature Endurance test of IEC 60384-14:2013 (4th edition) / UL 60384-14:2014 (2nd edition) must be performed at 1.25 × V_R at maximum temperature, during 1000 hours, with a capacitance drift less than 10%.
- Higher breakdown voltage withstanding if compared to other film metallizations, like Aluminum. IEC 60384-14:2013 (4th edition) / UL 60384-14:2014 (2nd edition) establishes high voltage tests performed at 4.3 × V_R −1 minute, impulse testing at 2500 V for C = 1 µF and active flammability tests.
- Damp heat steady state: 40 °C/ 93% RH / 56 days. (without voltage or current load)

Effect of humidity on capacitance stability

Long contact of a film capacitor with humidity can produce irreversible effects. Direct contact with liquid water or excess exposure to high ambient humidity or dew will eventually remove the film metallization and thus destroy the capacitor. Plastic boxed capacitors must be properly tested in the final application at the worst expected conditions of temperature and humidity in order to check if any parameter drift may provoke a circuit malfunction.

In case of penetration of humidity through the film, the layer of Zinc can be degraded, specially under AC operation (change of polarity), accelerated by the temperature, provoking an increment of the serial resistance of the electrode and eventually a reduction of the capacitance value. For DC operation, the parameter drift is much less.

Plastic boxes and resins can not protect 100% against humidity. Metal enclosures, resin potting or coatings or similar measures by customers in their applications will offer additional protection against humidity penetration.

Display of ordering codes for TDK Electronics products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications, on the company website, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the order-





ing codes are due to different processes employed and do not affect the specifications of the respective products.

Detailed information can be found on the Internet under

www.tdk-electronics.tdk.com/orderingcodes.





X2/305 V AC

Symbols and terms

Symbol	English	German
α	Heat transfer coefficient	Wärmeübergangszahl
α_{c}	Temperature coefficient of capacitance	Temperaturkoeffizient der Kapazität
Α	Capacitor surface area	Kondensatoroberfläche
βc	Humidity coefficient of capacitance	Feuchtekoeffizient der Kapazität
С	Capacitance	Kapazität
C _R	Rated capacitance	Nennkapazität
ΔC	Absolute capacitance change	Absolute Kapazitätsänderung
$\Delta C/C$	Relative capacitance change (relative deviation of actual value)	Relative Kapazitätsänderung (relative Abweichung vom Ist-Wert)
$\Delta C/C_B$	Capacitance tolerance (relative deviation	
$\Delta C/C_R$	from rated capacitance)	vom Nennwert)
dt	Time differential	Differentielle Zeit
Δt	Time interval	Zeitintervall
ΔT	Absolute temperature change	Absolute Temperaturänderung
	(self-heating)	(Selbsterwärmung)
∆tan δ	Absolute change of dissipation factor	Absolute Änderung des Verlustfaktors
ΔV	Absolute voltage change	Absolute Spannungsänderung
dV/dt	Time differential of voltage function (rate	Differentielle Spannungsänderung
	of voltage rise)	(Spannungsflankensteilheit)
$\Delta V / \Delta t$	Voltage change per time interval	Spannungsänderung pro Zeitintervall
E	Activation energy for diffusion	Aktivierungsenergie zur Diffusion
ESL	Self-inductance	Eigeninduktivität
ESR	Equivalent series resistance	Ersatz-Serienwiderstand
f	Frequency	Frequenz
f ₁	Frequency limit for reducing permissible	Grenzfrequenz für thermisch bedingte
	AC voltage due to thermal limits	Reduzierung der zulässigen
		Wechselspannung
f ₂	Frequency limit for reducing permissible	Grenzfrequenz für strombedingte
	AC voltage due to current limit	Reduzierung der zulässigen
		Wechselspannung
f _r	Resonant frequency	Resonanzfrequenz
F _D	Thermal acceleration factor for diffusion	Therm. Beschleunigungsfaktor zur Diffusion
F _τ	Derating factor	Deratingfaktor
i	Current (peak)	Stromspitze
I _C	Category current (max. continuous	Kategoriestrom (max. Dauerstrom)
	current)	





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Symbol	English	German
I _{RMS}	(Sinusoidal) alternating current,	(Sinusförmiger) Wechselstrom
	root-mean-square value	
i _z	Capacitance drift	Inkonstanz der Kapazität
k _o	Pulse characteristic	Impulskennwert
Ls	Series inductance	Serieninduktivität
λ	Failure rate	Ausfallrate
λο	Constant failure rate during useful	Konstante Ausfallrate in der
	service life	Nutzungsphase
λ_{test}	Failure rate, determined by tests	Experimentell ermittelte Ausfallrate
P_{diss}	Dissipated power	Abgegebene Verlustleistung
P_{gen}	Generated power	Erzeugte Verlustleistung
Q	Heat energy	Wärmeenergie
ρ	Density of water vapor in air	Dichte von Wasserdampf in Luft
R	Universal molar constant for gases	Allg. Molarkonstante für Gas
R	Ohmic resistance of discharge circuit	Ohmscher Widerstand des
		Entladekreises
R _i	Internal resistance	Innenwiderstand
R _{ins}	Insulation resistance	Isolationswiderstand
R _P	Parallel resistance	Parallelwiderstand
R _s	Series resistance	Serienwiderstand
S	severity (humidity test)	Schärfegrad (Feuchtetest)
t	Time	Zeit
Т	Temperature	Temperatur
τ	Time constant	Zeitkonstante
tan δ	Dissipation factor	Verlustfaktor
$tan \ \delta_{\text{D}}$	Dielectric component of dissipation factor	Dielektrischer Anteil des Verlustfaktors
tan δ_P	Parallel component of dissipation factor	Parallelanteil des Verlfustfaktors
tan δ_s	Series component of dissipation factor	Serienanteil des Verlustfaktors
T _A	Temperature of the air surrounding the component	Temperatur der Luft, die das Bauteil umgibt
T _{max}	Upper category temperature	Obere Kategorietemperatur
T _{min}	Lower category temperature	Untere Kategorietemperatur
t _{oL}	Operating life at operating temperature	Betriebszeit bei Betriebstemperatur und
	and voltage	-spannung
T _{op}	Operating temperature, $T_A + \Delta T$	Beriebstemperatur, $T_A + \Delta T$
T _R	Rated temperature	Nenntemperatur
T _{ref}	Reference temperature	Referenztemperatur
t _{SL}	Reference service life	Referenz-Lebensdauer





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Symbol	English	German
V _{AC}	AC voltage	Wechselspannung
V _c	Category voltage	Kategoriespannung
$V_{C,RMS}$	Category AC voltage	(Sinusförmige)
		Kategorie-Wechselspannung
V_{CD}	Corona-discharge onset voltage	Teilentlade-Einsatzspannung
V_{ch}	Charging voltage	Ladespannung
V _{DC}	DC voltage	Gleichspannung
V_{FB}	Fly-back capacitor voltage	Spannung (Flyback)
Vi	Input voltage	Eingangsspannung
Vo	Output voltage	Ausgangssspannung
V_{op}	Operating voltage	Betriebsspannung
V _p	Peak pulse voltage	Impuls-Spitzenspannung
V_{pp}	Peak-to-peak voltage Impedance	Spannungshub
V _R	Rated voltage	Nennspannung
ν _R	Amplitude of rated AC voltage	Amplitude der Nenn-Wechselspannung
V_{RMS}	(Sinusoidal) alternating voltage,	(Sinusförmige) Wechselspannung
	root-mean-square value	
V_{SC}	S-correction voltage	Spannung bei Anwendung "S-correction"
V_{sn}	Snubber capacitor voltage	Spannung bei Anwendung
		"Beschaltung"
Z	Impedance	Scheinwiderstand
е	Lead spacing	Rastermaß



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- 2. We also point out that in individual cases, a malfunction of electronic components or failure before the end of their usual service life cannot be completely ruled out in the current state of the art, even if they are operated as specified. In customer applications requiring a very high level of operational safety and especially in customer applications in which the malfunction or failure of an electronic component could endanger human life or health (e.g. in accident prevention or lifesaving systems), it must therefore be ensured by means of suitable design of the customer application or other action taken by the customer (e.g. installation of protective circuitry or redundancy) that no injury or damage is sustained by third parties in the event of malfunction or failure of an electronic component.
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- 6. Unless otherwise agreed in individual contracts, all orders are subject to our General Terms and Conditions of Supply.



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